MA22D23

Silicon epitaxial planar type

For high frequency rectification

■ Features

- $I_{F(AV)} = 1$ A rectification is possible.
- High I_{FSM} ($I_{FSM} = 30 A$)
- Small reverse current I_R.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	25	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Forward current (Average) *1	I _{F(AV)}	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T _j	150	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *1: Mounted on a alumina PC board

■ Package

- Code
 - Mini2-F1
- Pin Name
 - 1: Anode
- 2: Cathode

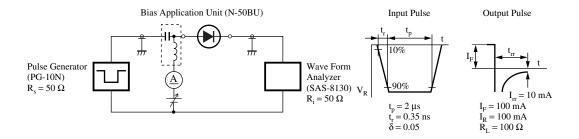
■ Marking Symbol: 3W

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

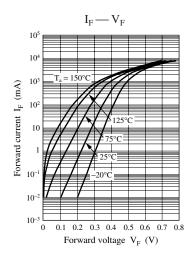
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I_{R1}	$V_R = 15 \text{ V}$		1.5	20	μΑ
	I_{R2}	$V_R = 20 \text{ V}$		2.5	40	
Forward voltage	V_{F1}	$I_F = 0.5 \text{ A}$		0.41	0.46	V
	V _{F2}	$I_F = 1.0 \text{ A}$		0.44	0.53	
Terminal capacitance	C _t	$V_R = 10 \text{ V}, \text{ f} = 1 \text{ MHz}$		45		pF

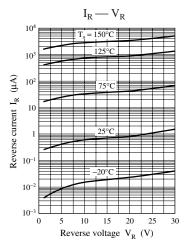
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

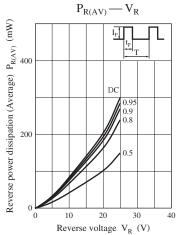
This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

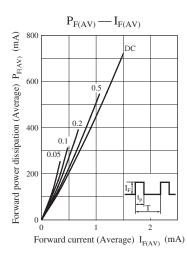


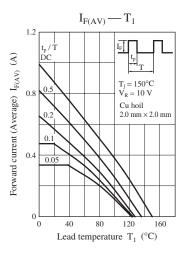
^{*2:} The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)





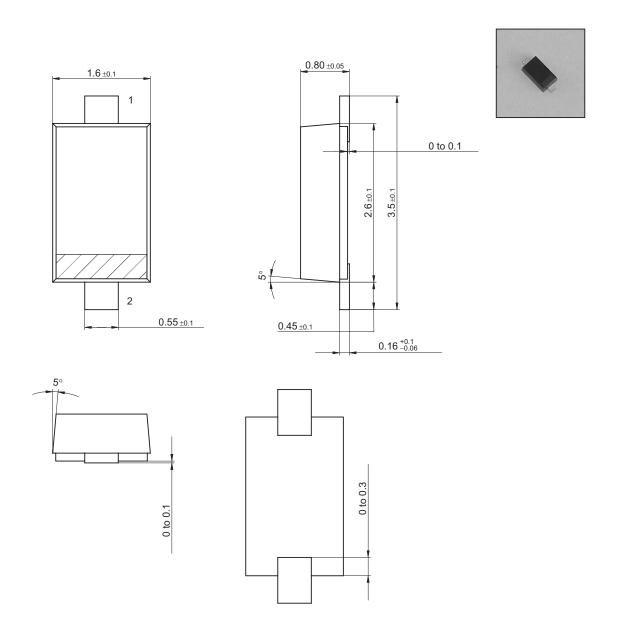






2 SKH00127BED

Mini2-F1 Unit: mm



SKH00127BED 3

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